

# FLM5964-25F

## C-Band Internally Matched FET

### FEATURES

- High Output Power:  $P_{1dB} = 44.5\text{dBm}$  (Typ.)
- High Gain:  $G_{1dB} = 10.0\text{dB}$  (Typ.)
- High PAE:  $\eta_{add} = 37\%$  (Typ.)
- Low  $IM_3 = -46\text{dBc}$  @  $P_o = 33.5\text{dBm}$
- Broad Band: 5.9 ~ 6.4GHz
- Impedance Matched  $Z_{in}/Z_{out} = 50\Omega$
- Hermetically Sealed Package

### DESCRIPTION

The FLM5964-25F is a power GaAs FET that is internally matched for standard communication bands to provide optimum power and gain in a 50 ohm system.

Fujitsu's stringent Quality Assurance Program assures the highest reliability and consistent performance.

### ABSOLUTE MAXIMUM RATING (Ambient Temperature $T_a=25^\circ\text{C}$ )

Item	Symbol	Condition	Rating	Unit
Drain-Source Voltage	$V_{DS}$		15	V
Gate-Source Voltage	$V_{GS}$		-5	V
Total Power Dissipation	$P_T$	$T_C = 25^\circ\text{C}$	93.7	W
Storage Temperature	$T_{stg}$		-65 to +175	$^\circ\text{C}$
Channel Temperature	$T_{ch}$		175	$^\circ\text{C}$

Fujitsu recommends the following conditions for the reliable operation of GaAs FETs:

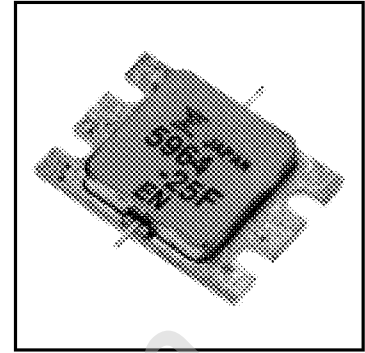
1. The drain-source operating voltage ( $V_{DS}$ ) should not exceed 10 volts.
2. The forward and reverse gate currents should not exceed 64.0 and -11.2 mA respectively with gate resistance of 25 $\Omega$ .

### ELECTRICAL CHARACTERISTICS (Ambient Temperature $T_a=25^\circ\text{C}$ )

Item	Symbol	Test Conditions	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	$I_{DSS}$	$V_{DS} = 5\text{V}, V_{GS} = 0\text{V}$	-	10	15	A
Transconductance	$g_m$	$V_{DS} = 5\text{V}, I_{DS} = 6.5\text{A}$	-	10	-	S
Pinch-off Voltage	$V_p$	$V_{DS} = 5\text{V}, I_{DS} = 500\text{mA}$	-0.5	-1.5	-3.0	V
Gate Source Breakdown Voltage	$V_{GSO}$	$I_{GS} = -500\mu\text{A}$	-5.0	-	-	V
Output Power at 1dB G.C.P.	$P_{1dB}$	$V_{DS} = 10\text{V},$ $I_{DS} = 0.65I_{DSS}$ (Typ.), $f = 5.9 \sim 6.4\text{GHz},$ $Z_S = Z_L = 50\text{ohm}$	43.5	44.5	-	dBm
Power Gain at 1dB G.C.P.	$G_{1dB}$		9.0	10.0	-	dB
Drain Current	$I_{dsr}$		-	6500	7600	mA
Power-added Efficiency	$\eta_{add}$		-	37	-	%
Gain Flatness	$\Delta G$		-	-	$\pm 0.6$	dB
3rd Order Intermodulation Distortion	$IM_3$	$f = 6.4\text{GHz}, \Delta f = 10\text{MHz}$ 2-Tone Test $P_{out} = 33.5\text{dBm}$ S.C.L.	-44	-46	-	dBc
Thermal Resistance	$R_{th}$	Channel to Case	-	1.4	1.6	$^\circ\text{C}/\text{W}$
Channel Temperature Rise	$\Delta T_{ch}$	$10\text{V} \times I_{dsr} \times R_{th}$	-	-	100	$^\circ\text{C}$

CASE STYLE: IK

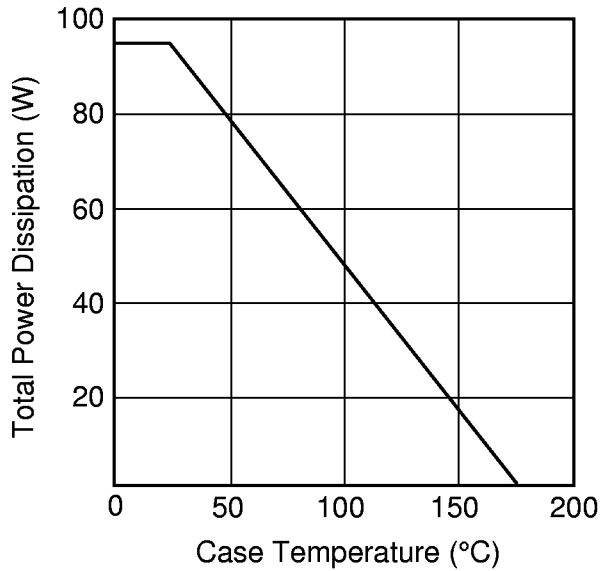
G.C.P.: Gain Compression Point, S.C.L.: Single Carrier Level



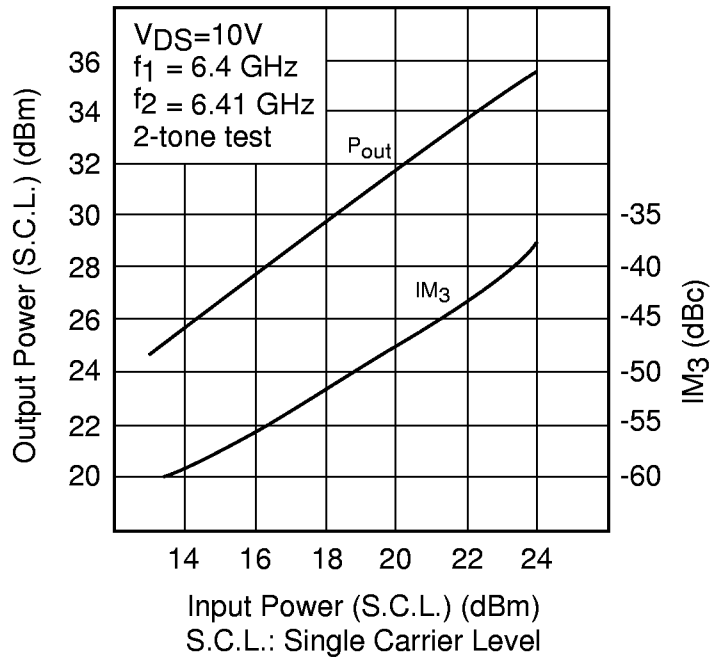
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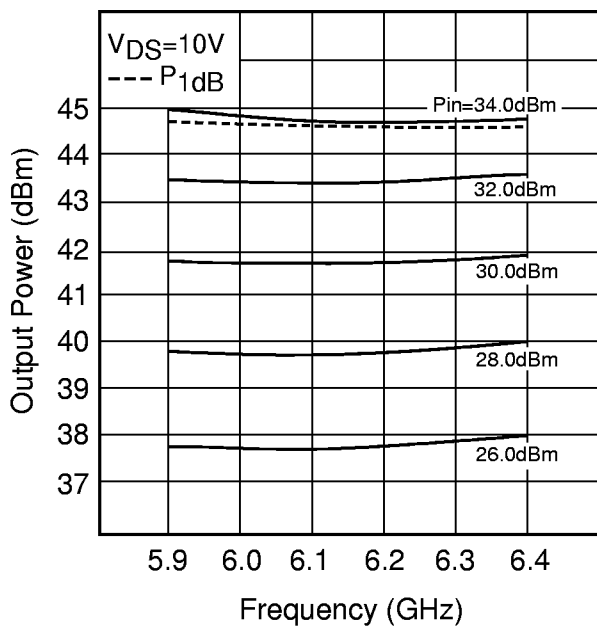
**POWER DERATING CURVE**



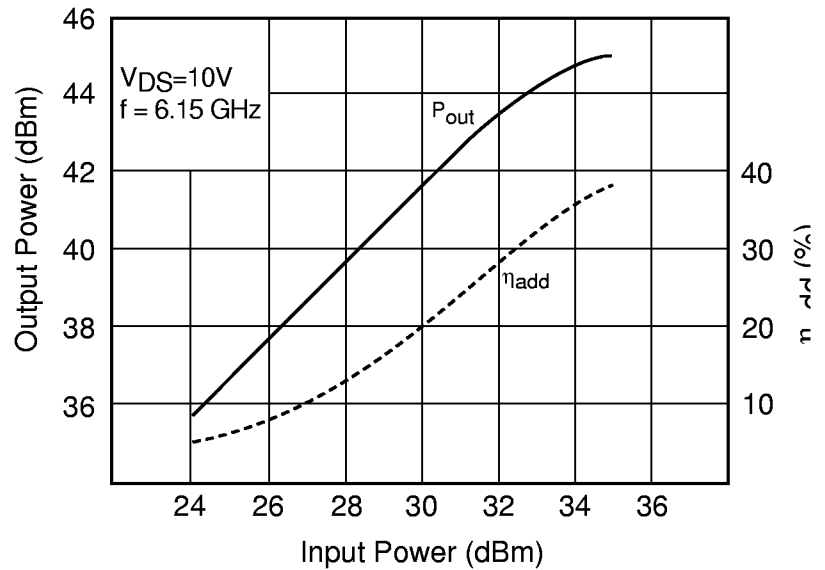
**OUTPUT POWER & IM<sub>3</sub> vs. INPUT POWER**



**OUTPUT POWER vs. FREQUENCY**

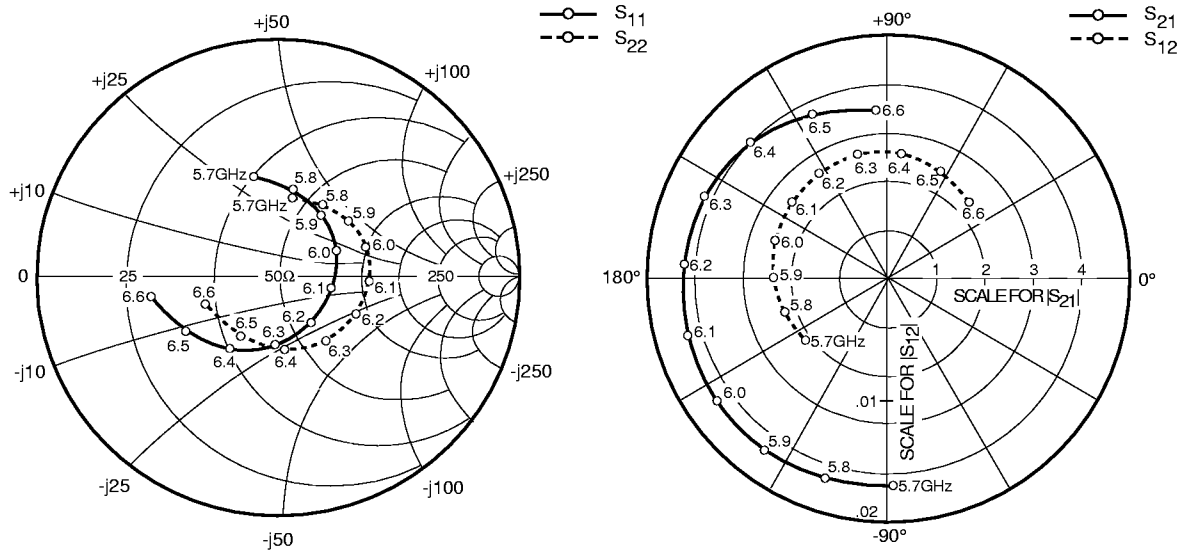


**OUTPUT POWER vs. INPUT POWER**



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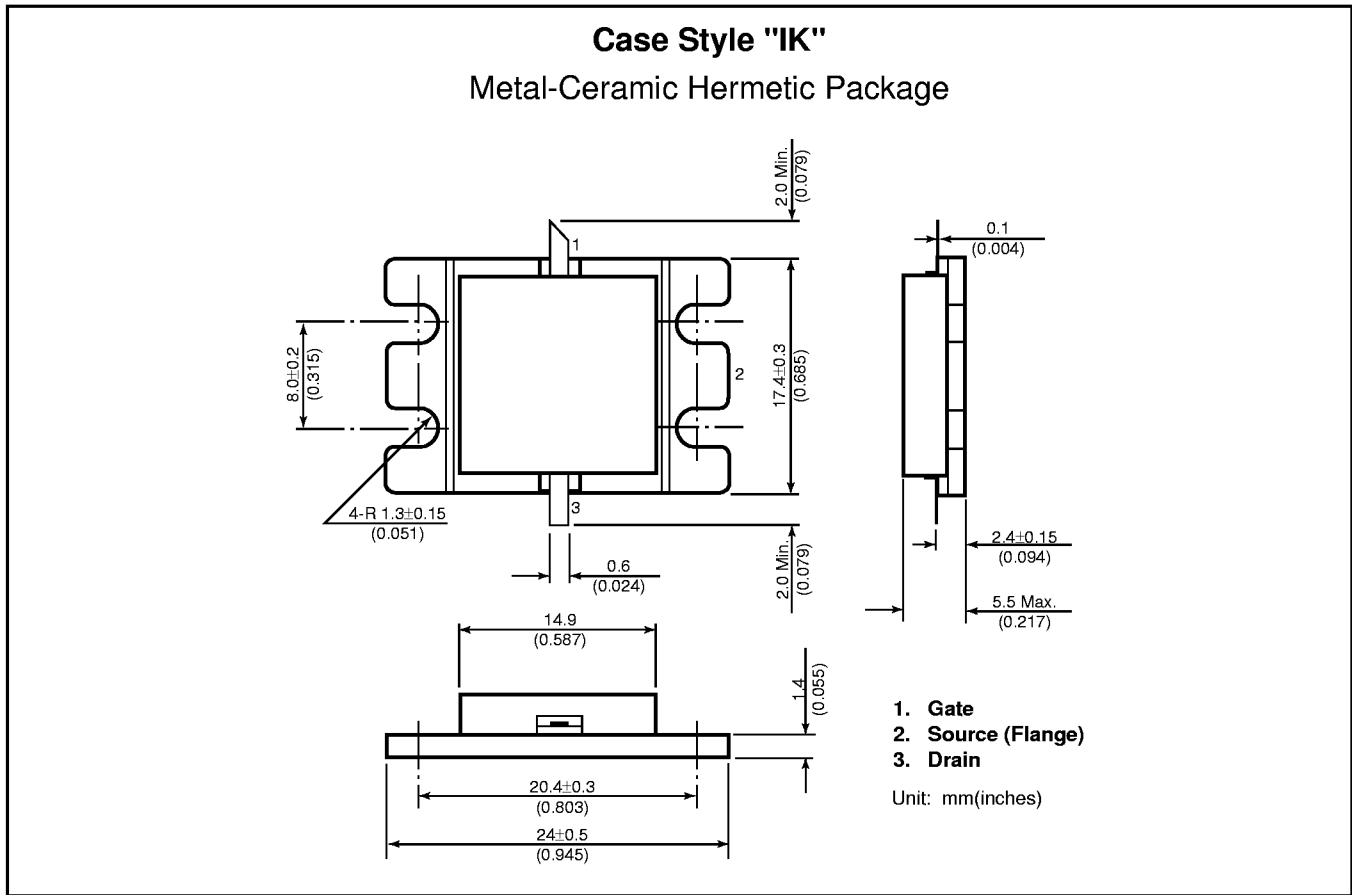
### S-PARAMETERS

$V_{DS} = 10V, I_{DS} = 6.5A$

FREQUENCY (MHZ)	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5700	.428	104.1	4.249	-89.0	.085	-144.0	.335	79.6
5800	.369	81.2	4.311	-107.4	.090	-162.3	.356	59.2
5900	.311	55.2	4.347	-126.1	.096	179.4	.371	38.7
6000	.261	24.5	4.354	-144.9	.099	161.1	.378	18.6
6100	.230	-13.9	4.333	-164.2	.103	142.1	.374	-3.1
6200	.240	-55.4	4.272	176.2	.105	123.1	.358	-26.4
6300	.290	-92.9	4.170	156.2	.106	103.7	.333	-53.6
6400	.365	-123.7	3.999	135.8	.103	84.0	.306	-85.1
6500	.451	-148.8	3.756	115.2	.099	63.8	.300	-122.1
6600	.538	-170.8	3.470	94.6	.092	43.7	.327	-159.3

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For further information please contact:

### FUJITSU COMPOUND SEMICONDUCTOR, INC.

2355 Zanker Rd.

San Jose, CA 95131-1138, U.S.A.

Phone: (408) 232-9500

FAX: (408) 428-9111

www.fcsi.fujitsu.com

### FUJITSU MICROELECTRONICS, LTD.

Compound Semiconductor Division

Network House

Norreys Drive

Maidenhead, Berkshire SL6 4FJ

Phone: +44 (0)1628 504800

FAX: +44 (0)1628 504888

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- Do not put these products into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

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